



**EFRE 2020**

7<sup>th</sup> International Congress  
Energy Fluxes and Radiation Effects

**N\*** Novosibirsk  
State  
University  
**\*THE REAL SCIENCE**

## **ALUMINIUM NITRIDE THIN FILMS SURFACE SMOOTHING BY ARGON CLUSTER IONS**

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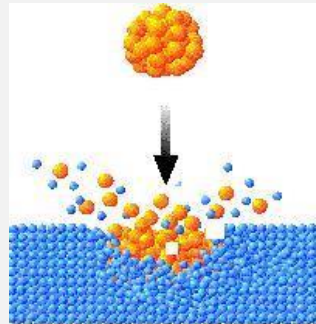
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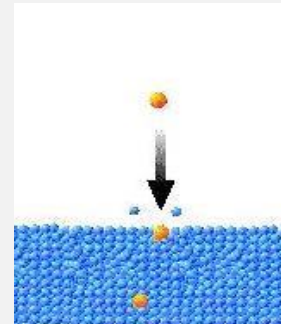
## Gas Cluster Ion Beam (GCIB)



**Collectively interaction**

VS

## Monomer ion beam



**Binary collisions**

### Complex nonlinear effects:

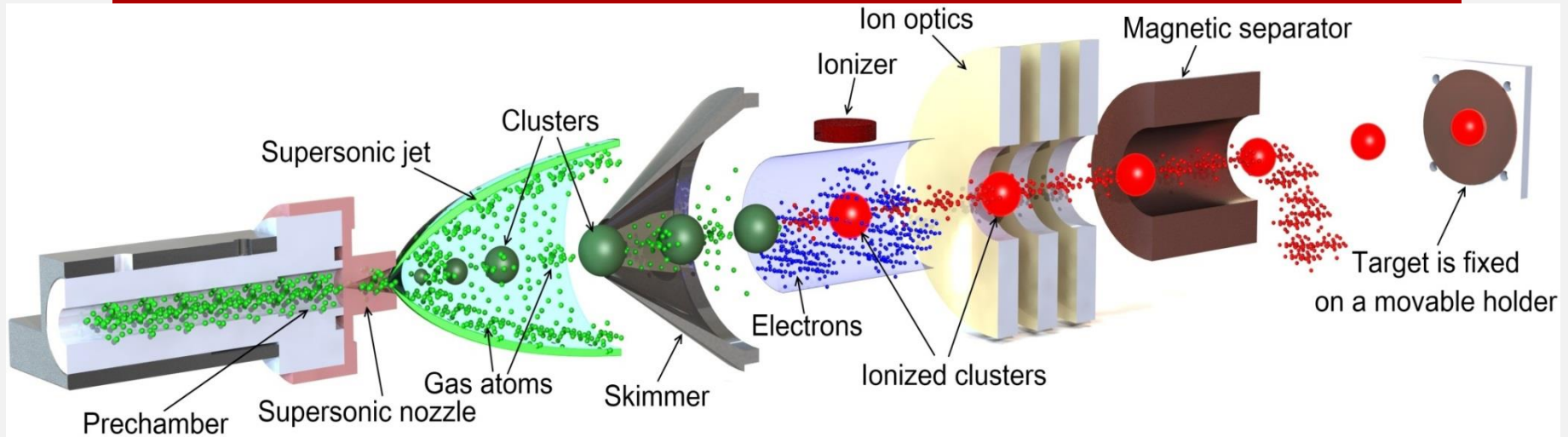
- **local high density of energy deposition** (local temperature up to  $10^5$  K, pressure up to 10 Mbar) in the subsurface layer, less than 20 nm deep;
- **lateral sputtering** leading to surface smoothing;
- **the energy per atom in a cluster can reach values  $<10$  eV**, which is comparable with the binding energy of atoms on the target surface, what leading to minimal damage to the subsurface material structure; this energy is unattainable in monomer ion beams.

### Material processing:

- surface smoothing and etching with low damage;
- the formation of self-organizing nanostructures;
- subsurface implantation;
- deposition of thin films.

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- **Material surface diagnostics:** secondary ion mass spectrometry using cluster ions (GCIB-SIMS).

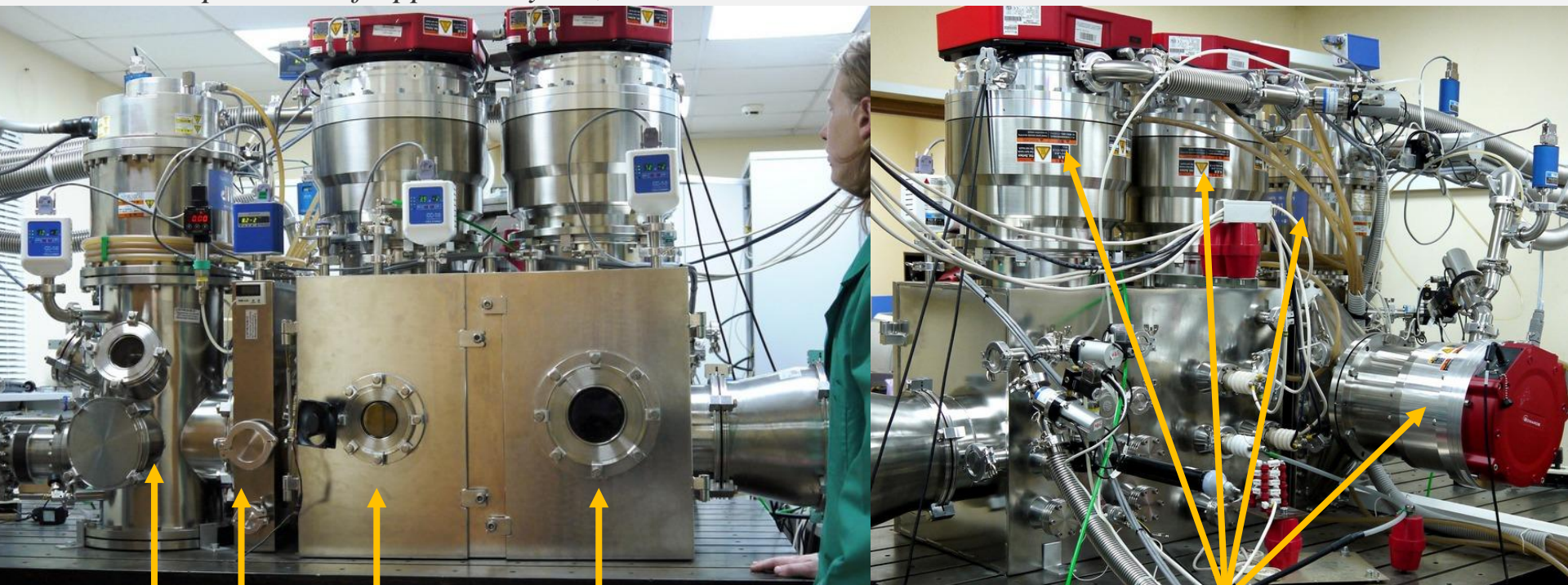


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## Main tasks and problems:

- Formation of a neutral cluster beam with the required cluster size and maximum intensity
  - Highly efficient electron beam ionization of neutral clusters with minimal fragmentation
  - Acceleration and focusing of cluster ion beam
  - Separation of oligomer and monomers ions and transport of cluster ions to the target
  - **Formation of cluster ion beam with defined parameters (mean size, energy per atom in cluster)**
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expansion  
chamber

post-skimmer chamber

ionizer chamber

sample chamber

turbomolecular pumps  
2600×2 | 1600 | 2200 1/s [9000 1/s]

Experiment parameters:

**Working gas:** Argon

**Cluster energy:** 5-23.5 keV

**Mean cluster size:** 180-1000 atoms/cluster

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<b>Treatment mode</b>	<b>Mean cluster size N, atoms/cluster</b>	<b>Cluster ions energy E, keV</b>	<b>Energy per atom E/N, eV/atom</b>	<b>Ion fluence, ions/cm<sup>2</sup></b>
1 (high-energy)	210	22	105	$8.1 \times 10^{15}$
2 (low-energy)	1000	10	10	$2.2 \times 10^{16}$

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$$Y = \frac{N_{OUT}}{N_{IN}}$$

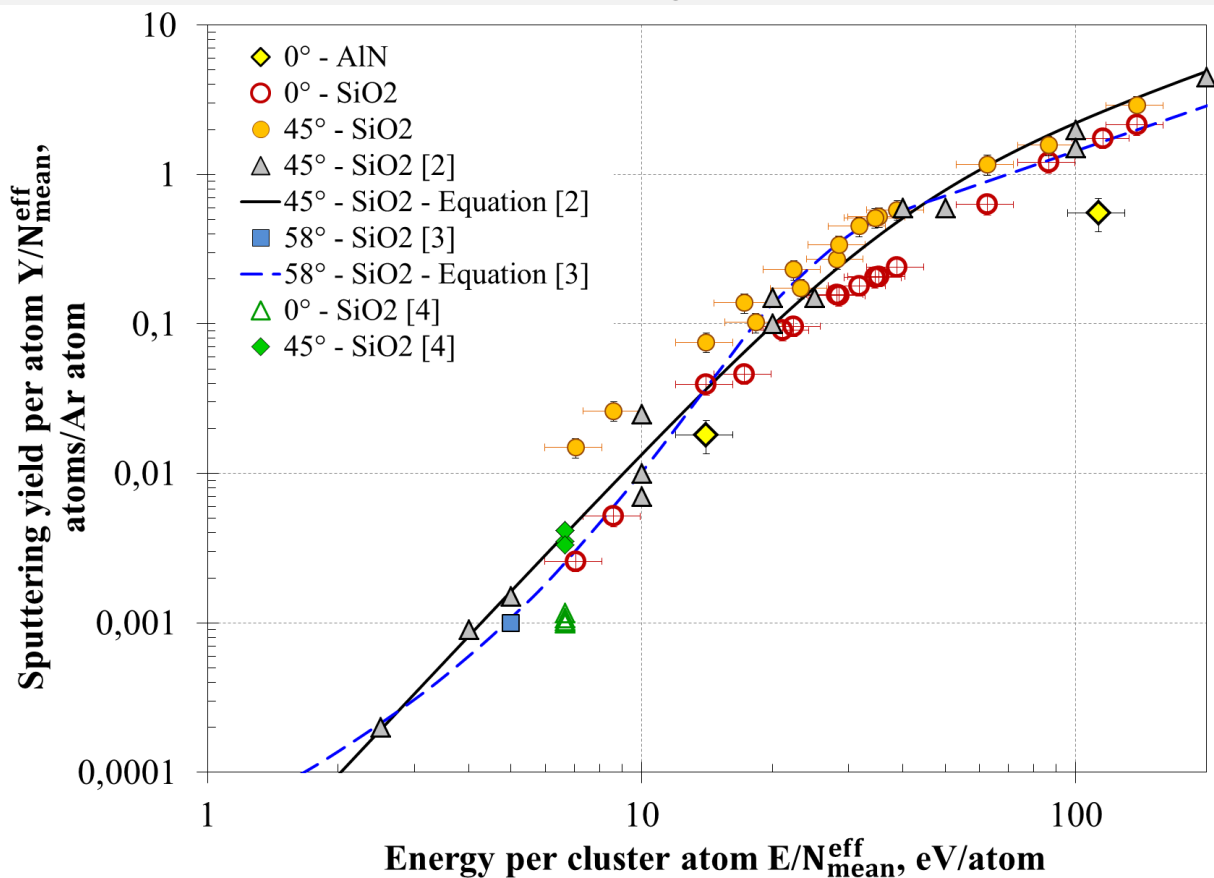
where  $N_{OUT}$  – the total number of sputtered target atoms during cluster bombardment  $Ar^+$ ;  
 $N_{IN}$  – the total number of  $Ar +$  cluster ions during the exposure;

Previously, in [1], we have shown that, at the normal incident angle of clusters, the GCIB sputtering process is determined by the energy per atom in the cluster  $E/N$ . Thus, as well as for oblique angles of incidence [2,3], the sputtering yields  $Y$  can be described as a universal nonlinear equation  $Y/N$  vs.  $E/N$  for clusters incident at a normal angle.

$$\frac{Y}{N} = \frac{(E/(AN))^q}{1 + (E/(AN))^{q-1}} \quad [2]$$

$$\frac{Y}{N} = EA \left[ 1 + \operatorname{erf} \left( \frac{E - U}{s} \right) \right] \quad [3]$$

where  $N$  – mean cluster size, atoms;  
 $E$  – kinetic cluster energy, eV;  
 $A, q, U, s$  – constants for specific materials.



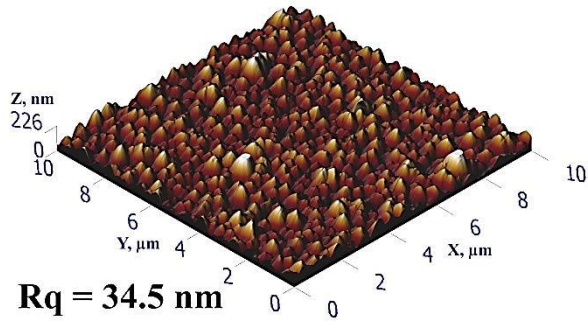
[1] N.G. Korobeishchikov et al. *Applied Physics A* 124 (2018) 833

[2] M.P. Seah. *J. Phys. Chem. C* 117 (2013) 12622

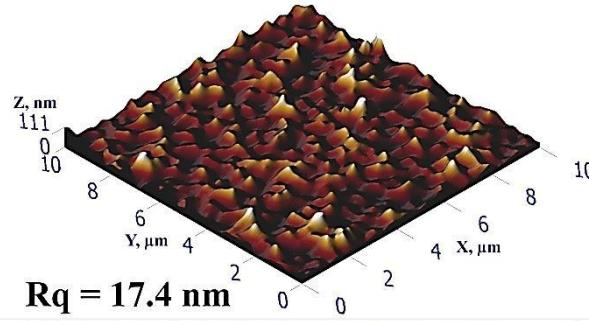
[3] P.J. Cumpson et al. *J. Appl. Phys.* 114 (2013) 124313

[4] K Sumie et al. *Nucl. Instr. Meth. Phys. Res. B* 307 (2013) 290

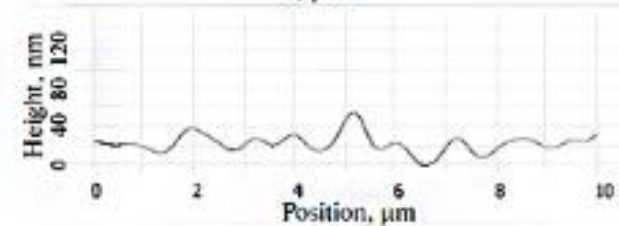
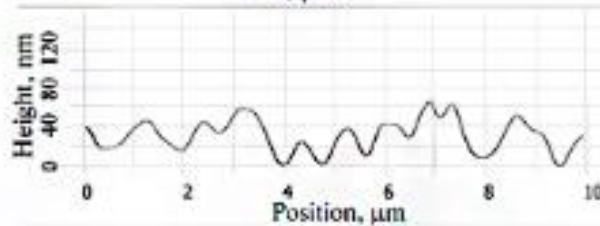
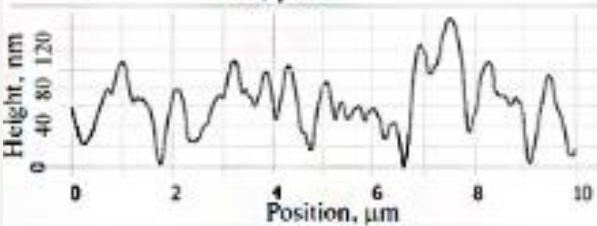
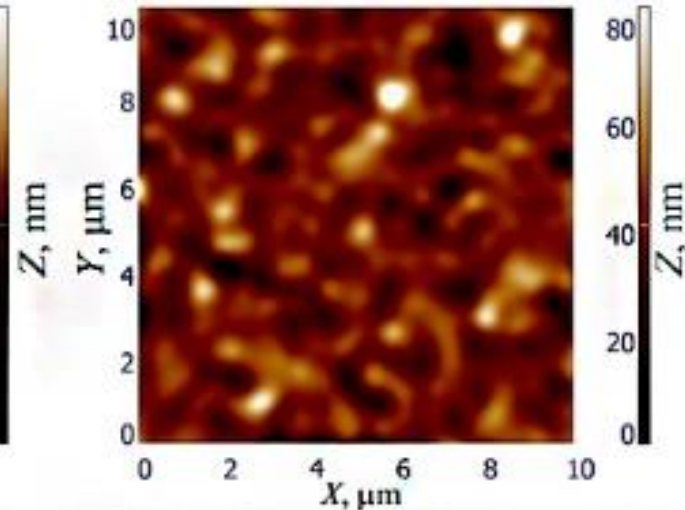
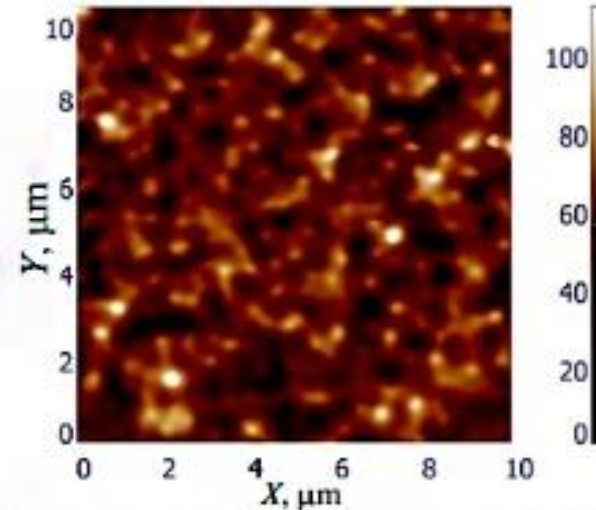
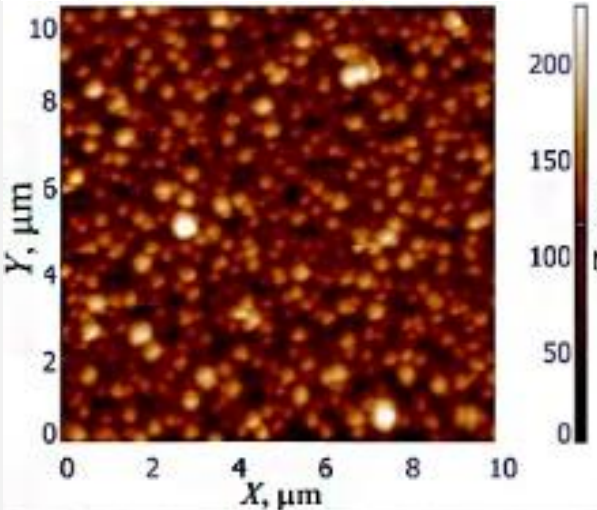
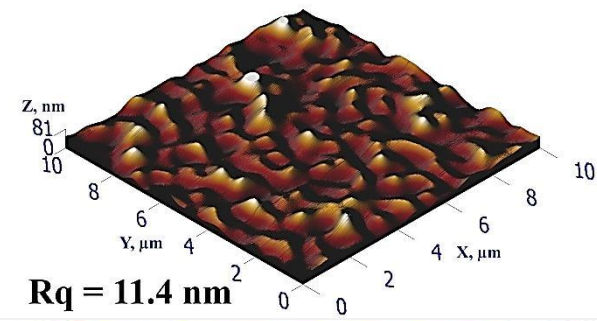
Initial



After high-energy mode

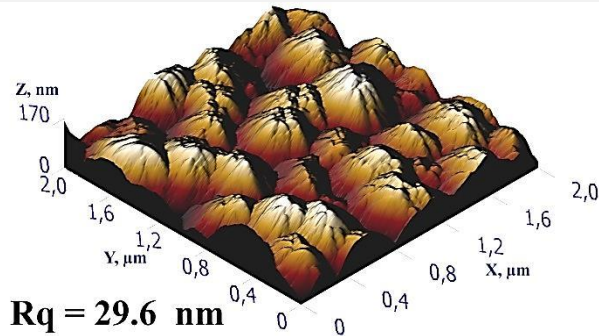


After low-energy mode

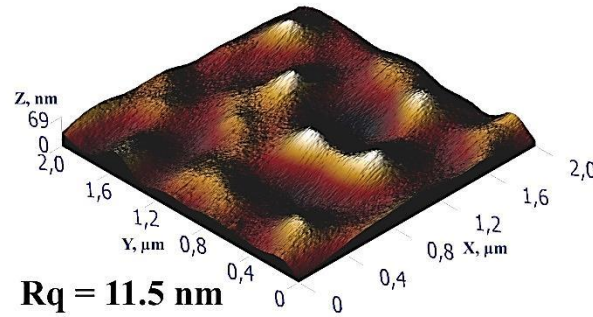


AFM images of AlN thin film surface at scan sizes  $10 \times 10 \mu\text{m}^2$ : initial and after cluster ions treatment.

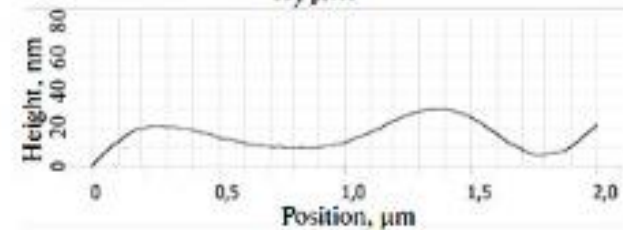
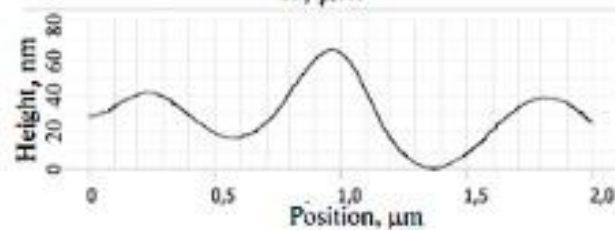
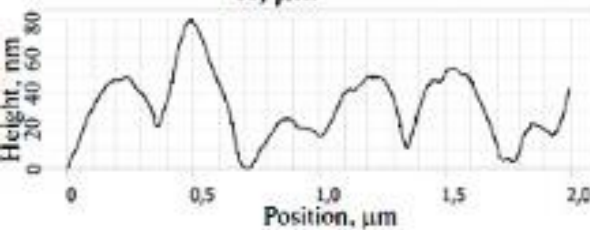
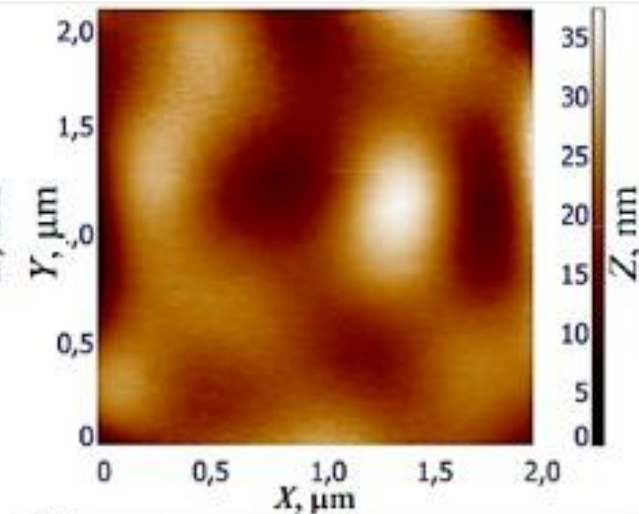
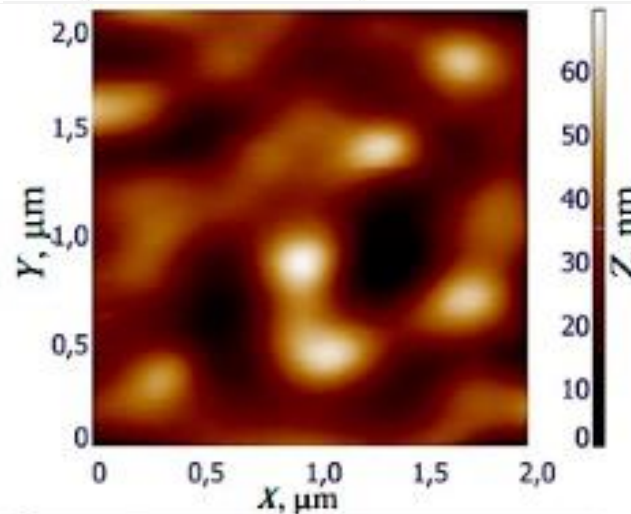
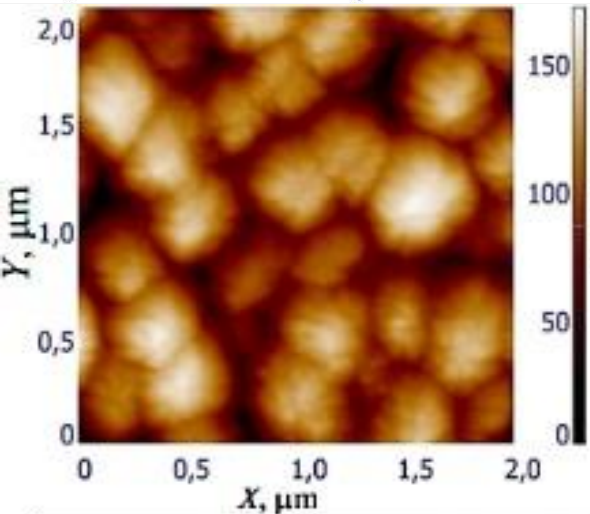
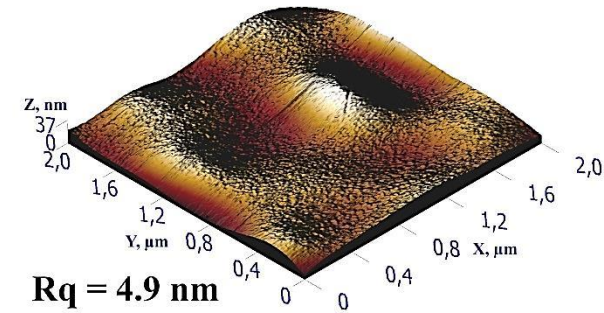
Initial



After high-energy mode



After low-energy mode



AFM images of AlN thin film surface at scan sizes  $2 \times 2 \mu\text{m}^2$ : initial and after cluster ions treatment.



To comparing the effectiveness of various treatment modes, it should be noted that the sputtering depth was 90 and 30 nm for modes 1 and 2, respectively.

Treatment mode	RMS roughness $R_q$ , nm	Maximum roughness $R_t$ , nm
Scan size $2 \times 2 \mu\text{m}^2$		
initial	29.2	169
after mode 1	9.9	61
after mode 2	<b>4.9</b>	<b>35</b>
Scan size $10 \times 10 \mu\text{m}^2$		
initial	35.0	222
after mode 1	16.8	107
after mode 2	<b>11.3</b>	<b>78</b>
Scan size $40 \times 40 \mu\text{m}^2$		
initial	26.4	176
after mode 1	14.3	97
after mode 2	<b>11.1</b>	<b>74</b>
Scan size $100 \times 100 \mu\text{m}^2$		
initial	21.3	144
after mode 1	12.3	92
after mode 2	<b>9.5</b>	<b>63</b>

- The surface treatment of a polycrystalline AlN thin film with argon cluster ions was performed in various experimental modes. The possibility of effective smoothing of a nanostructured AlN surface with a minimum depth of the sputtering layer and minimal damage to the subsurface structure of the processed material is proved.
  - It was shown that, after treatment mode 2, the root-mean-square roughness decreased in 2.2–6 times (depending on the scan size).
  - The highest efficient smoothing with very small sputtering depth (tens nm) is obtained in the low-energy treatment modes (few eV/atom), which is caused by active lateral displacement of subsurface target atoms.
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**Thank you for  
your attention!**

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